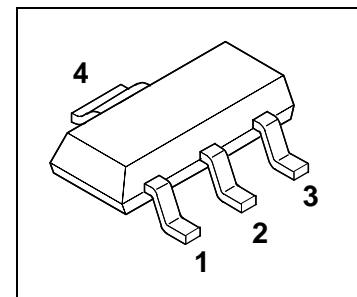


MiniPROFET

- High-side switch
- Short-circuit protection
- Input protection
- Overtemperature protection with hysteresis
- Overload protection
- Ovvoltage protection
- Switching inductive load
- Clamp of negative output voltage with inductive loads
- Undervoltage shutdown
- Maximum current internally limited
- **Electrostatic discharge (ESD) protection**
- Reverse battery protection¹⁾



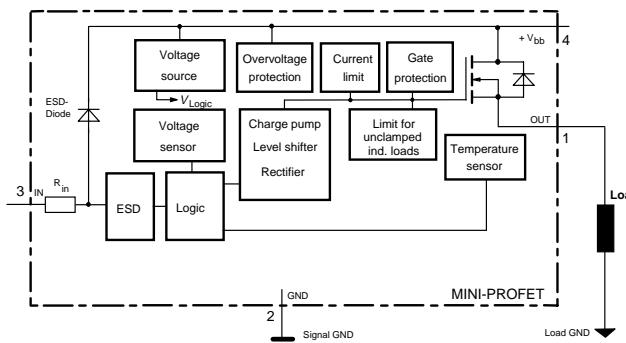
Package: SOT 223

Type	Ordering code
BSP 550	Q67000-S311

Pins			
1	2	3	4
OUT	GND	IN	V_{bb}

Maximum Ratings

Parameter	Symbol	Values	Unit
Supply voltage range	V_{bb}	-0.3...48	V
Load current	I_L	$I_{L(SC)}$	A
Maximum input voltage ²⁾	V_{IN}	-5.0... V_{bb}	V
Maximum input current	I_{IN}	± 5	mA
Inductive load switch-off energy dissipation single pulse	E_{AS}	0.3	J
Operating temperature range	T_j	-40 ...+125	°C
Storage temperature range	T_{stg}	-55 ...+150	
Max. power dissipation (DC) ³⁾	P_{tot}	1.4	W
Electrostatic discharge capability (ESD) ⁴⁾	V_{ESD}	± 1	kV
Thermal resistance chip - soldering point: chip - ambient ³⁾	R_{thJS} R_{thJA}	7 70	K/W



1) With resistor $R_{GND}=150 \Omega$ in GND connection, resistor in series with IN connections reverse load current limited by connected load.

2) At $V_{IN} > V_{bb}$, the input current is not allowed to exceed ± 5 mA.

3) BSP 550 on epoxy pcb 40 mm x 40 mm x 1.5 mm with 6 cm^2 copper area for V_{bb} connection

4) HBM according to MIL-STD 883D, Methode 3015.7

Electrical Characteristics

Parameter and Conditions at $T_j = 25^\circ\text{C}$, $V_{bb} = 24\text{V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Load Switching Capabilities and Characteristics

On-state resistance (pin 4 to 1) $I_L = 1.0 \text{ A}$, $V_{in} = \text{high}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	R_{ON}	-- --	0.16 --	0.2 0.38	Ω
Nominal load current (pin 4 to 1) ⁵⁾ ISO Standard: $V_{ON} = V_{bb} - V_{OUT} = 0.5 \text{ V}$ $T_S = 85^\circ\text{C}$	$I_{L(\text{ISO})}$	1.4	--	--	A
Turn-on time Turn-off time $R_L = 24 \Omega$	t_{on} t_{off}	-- --	60 90	100 150	μs
Slew rate on 10 to 30% V_{OUT} , $R_L = 24 \Omega$	dV/dt_{on}	--	2	4	$\text{V}/\mu\text{s}$
Slew rate off 70 to 40% V_{OUT} , $R_L = 24 \Omega$	$-dV/dt_{off}$	--	2	4	$\text{V}/\mu\text{s}$

Input

Allowable input voltage range, (pin 3 to 2)	V_{IN}	-3.0	--	V_{bb}	V
Input turn-on threshold voltage $V_{bb} = 18 \dots 30\text{V}$ $T_j = -25 \dots +125^\circ\text{C}$	$V_{IN(T+)}$	--	--	3.0	V
Input turn-off threshold voltage $V_{bb} = 18 \dots 30\text{V}$ $T_j = -25 \dots +125^\circ\text{C}$	$V_{IN(T-)}$	1.82	--	--	V
Input threshold hysteresis	$\Delta V_{IN(T)}$	--	0.1	--	V
Off state input current (pin 3) $V_{IN(off)} = 1.82 \text{ V}$ $T_j = -25 \dots +125^\circ\text{C}$	$I_{IN(off)}$	20	--	--	μA
On state input current (pin 3) $V_{IN(on)} = 3.0 \text{ V to } V_{bb}$ $T_j = -25 \dots +125^\circ\text{C}$	$I_{IN(on)}$	--	--	110	μA
Input resistance $T_j = -25 \dots +125^\circ\text{C}$	R_{IN}	1.5	2.8	3.5	$\text{k}\Omega$

⁵⁾ $I_{L(\text{ISO})}$ is limited by the current limitation, see $I_{L(\text{SC})}$

Parameter and Conditions at $T_j = 25^\circ\text{C}$, $V_{bb} = 24\text{V}$ unless otherwise specified	Symbol	Values			Unit
		min	typ	max	

Operating Parameters

Operating voltage	$T_j = -25\ldots+125^\circ\text{C}$	$V_{bb(on)}$	12		40	V
Undervoltage shutdown	$T_j = -25\ldots+125^\circ\text{C}$	$V_{bb(under)}$	7	--	10.5	V
Undervoltage restart	$T_j = -25\ldots+125^\circ\text{C}$:	$V_{bb(u\ rst)}$	--	--	11	V
Undervoltage hysteresis		$\Delta V_{bb(under)}$	--	0.4	--	V
Standby current (pin 4), $V_{in} = \text{low}$	$T_j = -25\ldots+100^\circ\text{C}$	$I_{bb(off)}$	--	10	25	μA
	$T_j = 125^\circ\text{C}^6)$				50	
Operating current (pin 2), $V_{in} = \text{high}$	$T_j = -25\ldots+125^\circ\text{C}$	I_{GND}	--	1	1.6	mA
leakage current (pin 1) $V_{in} = \text{low}$	$T_j = -25\ldots+125^\circ\text{C}$	$I_{L(off)}$	--	--	2	μA

Protection Functions

Current limit (pin 4 to 1)	$T_j = 25^\circ\text{C}$	$I_{L(SC)}$	1.4	2.5	4.0	A
	$T_j = -25\ldots+125^\circ\text{C}$		1.4	--	4.8	
Ovvoltage protection $I_{bb}=4\text{mA}$	$T_j = -25\ldots+125^\circ\text{C}$	$V_{bb(AZ)}$	48	--	--	V
Output clamp (ind. load switch off) $V_{OUT} = V_{bb} - V_{ON(CL)}, I_{bb} = 4\text{mA}$		$V_{ON(CL)}$	--	72	--	V
Thermal overload trip temperature		T_{jt}	135	150	--	$^\circ\text{C}$
Thermal hysteresis		ΔT_{jt}	--	10	--	K
Inductive load switch-off energy dissipation ⁷⁾ $T_j \text{ Start} = 85^\circ\text{C}$, single pulse, $I_L = 1.0 \text{ A}$, $V_{bb} = 12 \text{ V}$		E_{AS}	--	--	0.3	J

Reverse Battery

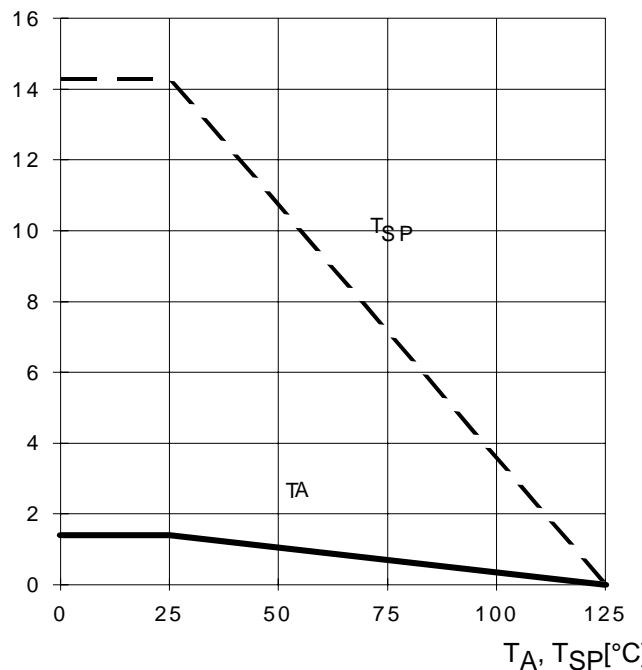
Reverse battery voltage ⁸⁾	$-V_{bb}$			30	V	
Continious reverse drain current	$T_A = 25^\circ\text{C}$	$-I_S$	--	--	1	A
Drain-Source diode voltage $I_F = 1 \text{ A}, V_{in} = \text{low}$	$V_{OUT} > V_{bb}$	$-V_{ON}$	--	--	1.2	V

6) increase of standby current at $T_j = 125^\circ\text{C}$ caused by temperature sense current7) while demagnetizing load inductance, dissipated energy is $E_{AS} = \int (V_{ON(CL)} * i_L(t)) dt$,
approx. $E_{AS} = 1/2 * L * I_L^2 * (\frac{V_{ON(CL)}}{V_{ON(CL)} - V_{bb}})$ 8) Requires 150 Ω resistor in GND connection. Reverse load current (through intrinsic drain-source diode) is normally limited by the connected load.

Max allowable power dissipation

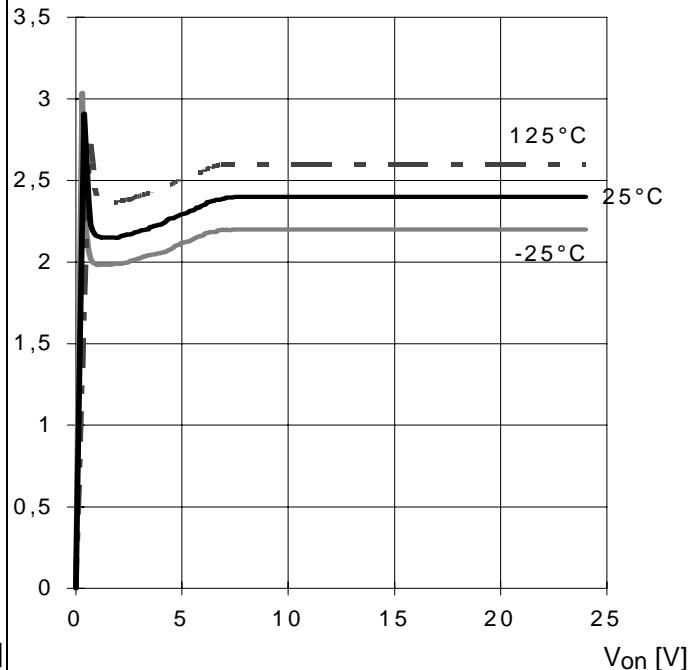
$$P_{\text{tot}} = f(T_A, T_{SP})$$

P_{tot} [W]

**Current limit characteristic**

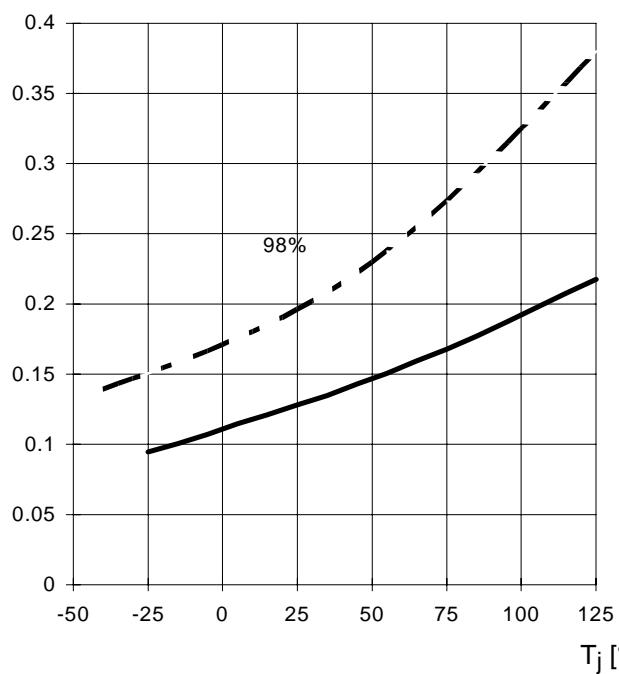
$$I_L(\text{SC}) = f(V_{\text{on}}), (V_{\text{on}} \text{ see testcircuit})$$

$I_L(\text{SC})$ [A]

**On state resistance (V_{bb}-pin to OUT pin)**

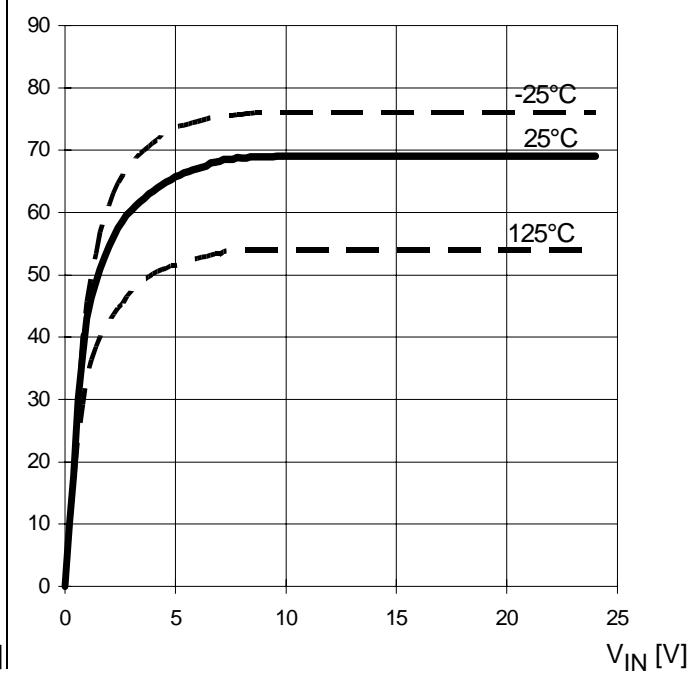
$$R_{\text{ON}} = f(T_j); V_{\text{bb}} = 24 \text{ V}; I_L = 1.0 \text{ A}$$

R_{ON} [Ω]

**Typ. input current**

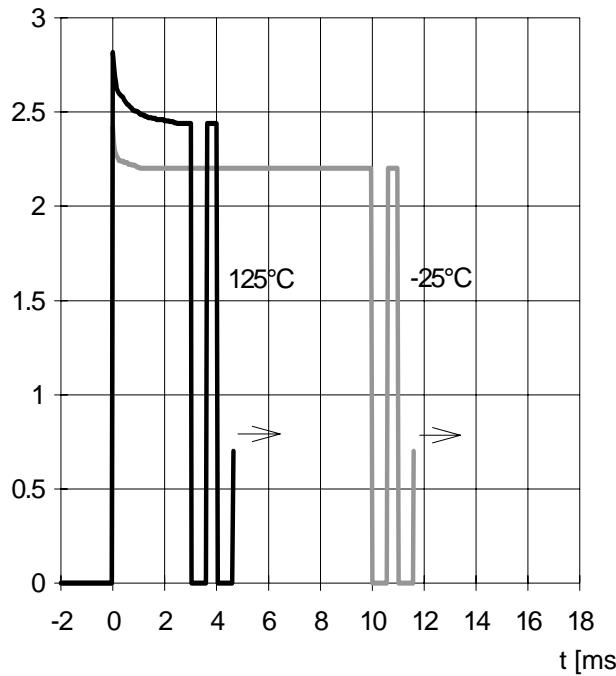
$$I_{\text{IN}} = f(V_{\text{IN}}); V_{\text{bb}} = 24 \text{ V}$$

I_{IN} [μA]



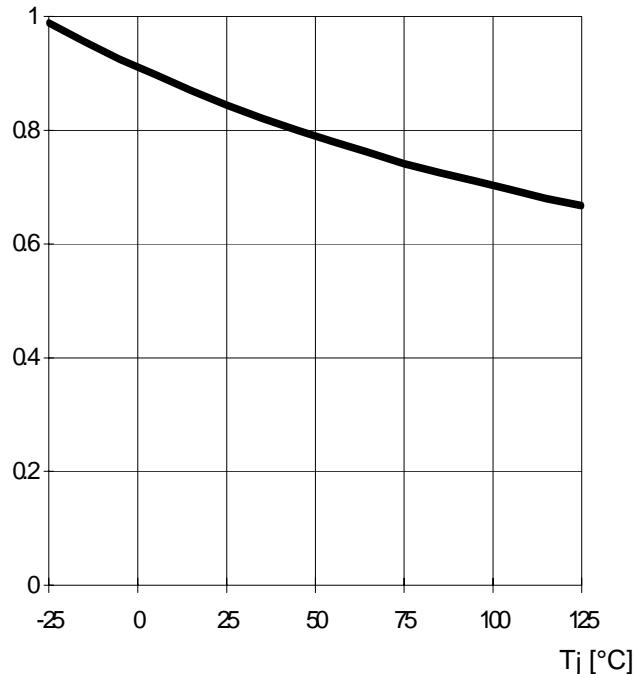
Typ. overload current

$I_L(\text{lim}) = f(t)$, $V_{bb} = 24V$, no heatsink, Param.: $T_{j\text{start}}$
 $I_L(\text{lim}) [\text{A}]$



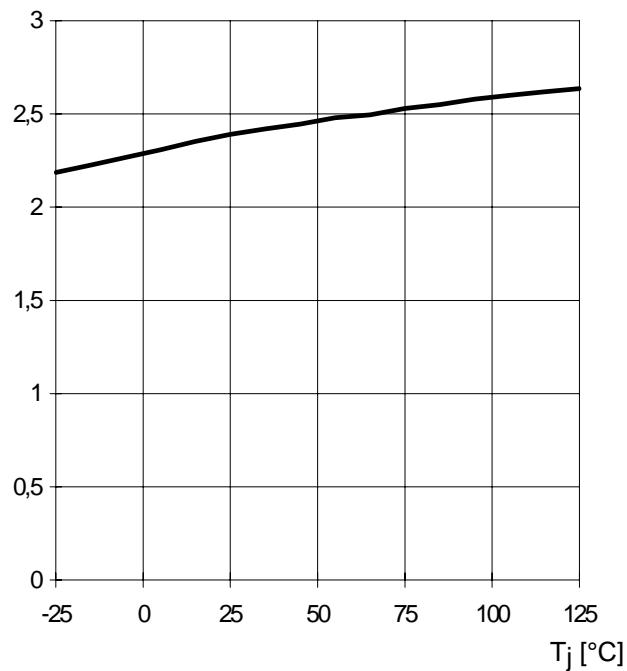
Typ. operating current

$I_{GND} = f(T_j)$, $V_{bb} = 30V$, $V_{IN} = \text{high}$
 $I_{GND} [\text{mA}]$



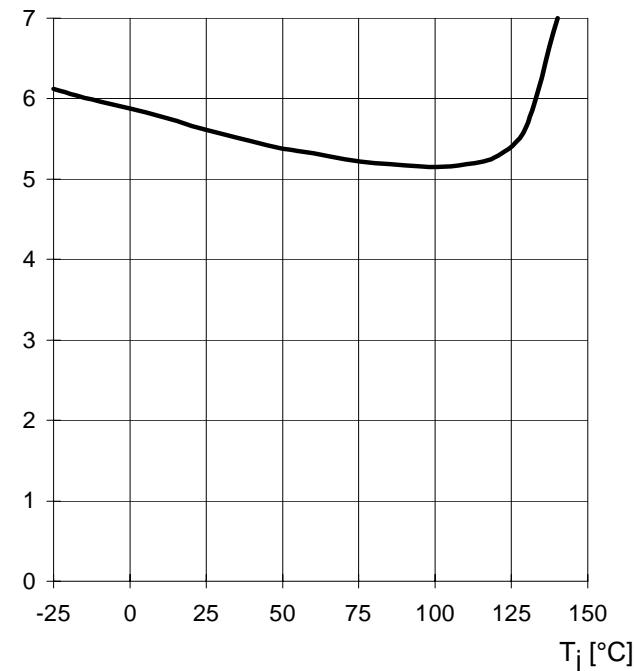
Short circuit current

$I_L(SC) = f(T_j)$; $V_{bb} = 30V$;
 $I_L(SC) [\text{A}]$



Typ. standby current

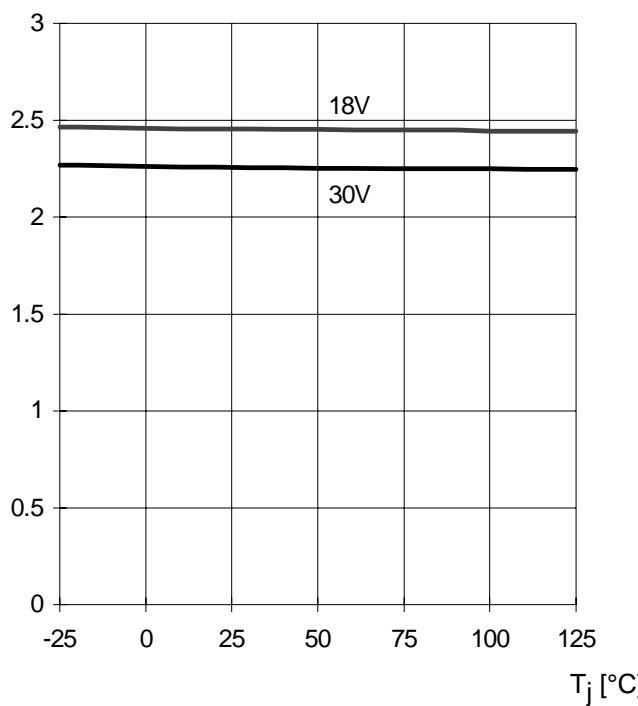
$I_{bb(\text{off})} = f(T_j)$; $V_{bb} = 30V$, $V_{IN} = \text{low}$
 $I_{bb(\text{off})} [\mu\text{A}]$



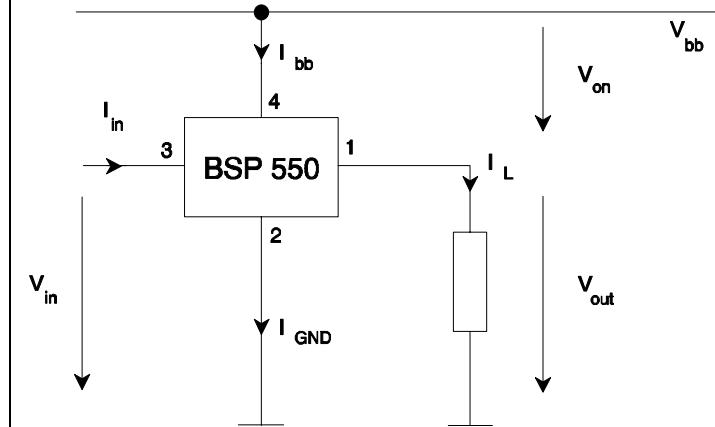
Typ. input turn on voltage threshold

$$V_{IN(T+)} = f(T_j)$$

$V_{IN(T+)} [V]$



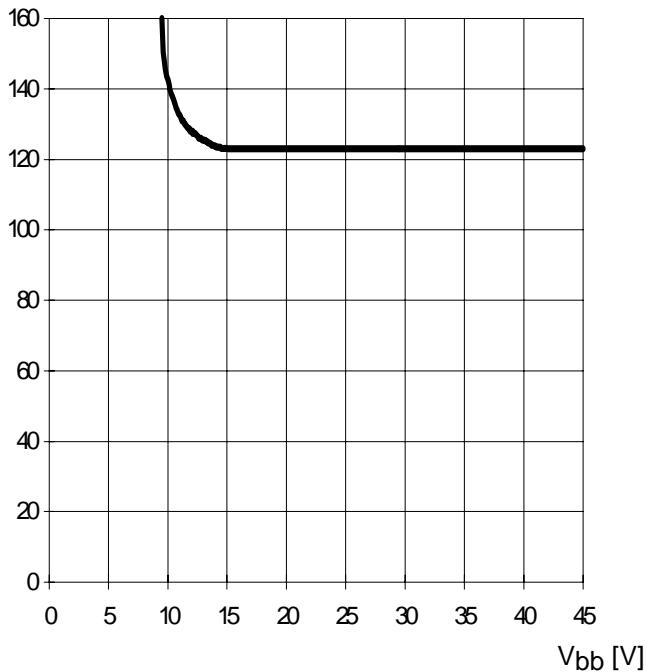
Test circuit



Typ. on-state resistance (Vbb-Pin to OUT-Pin)

$$R_{ON} = f(V_{bb}); I_L = 1.0A, T_j = 25^{\circ}C;$$

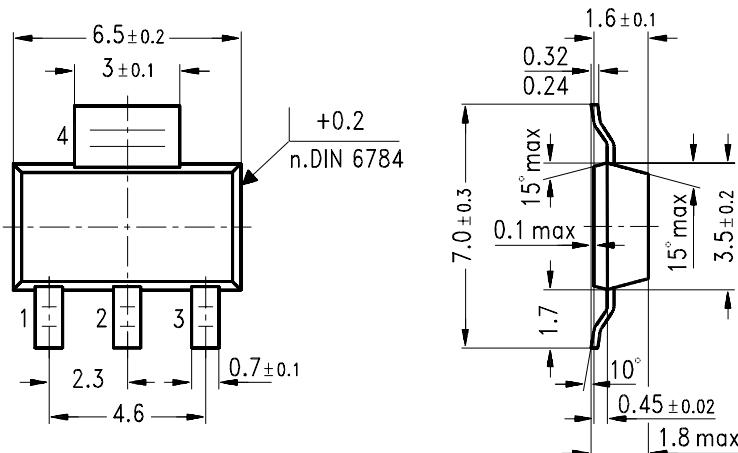
R_{ON} [$m\Omega$]



Package:

all dimensions in mm.

SOT 223/4:



GPS05560

Edition 7.97

**Published by Siemens AG,
Bereich Halbleiter Vertrieb,
Werbung, Balanstraße 73,
81541 München**

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